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(12) **United States Design Patent** (10) **Patent No.:** **US D895,076 S**
Kuroda et al. (45) **Date of Patent:** **** Sep. 1, 2020**

(54) **COMPOSITE SEAL MEMBER FOR SEMICONDUCTOR PRODUCTION APPARATUS**

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(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (12) Cl.** **23-01**

(52) **U.S. Cl.**
USPC **D23/269**

(58) **Field of Classification Search**
USPC D23/269; D8/382

(Continued)

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(Continued)

(57) **CLAIM**

The ornamental design for a composite seal member for semiconductor production apparatus, as shown and described.

DESCRIPTION

1. Composite seal member for semiconductor production apparatus

1.1 : Perspective

1.2 : Front

1.3 : Back

1.4 : Left

1.5 : Right

1.6 : Top

1.7 : Bottom

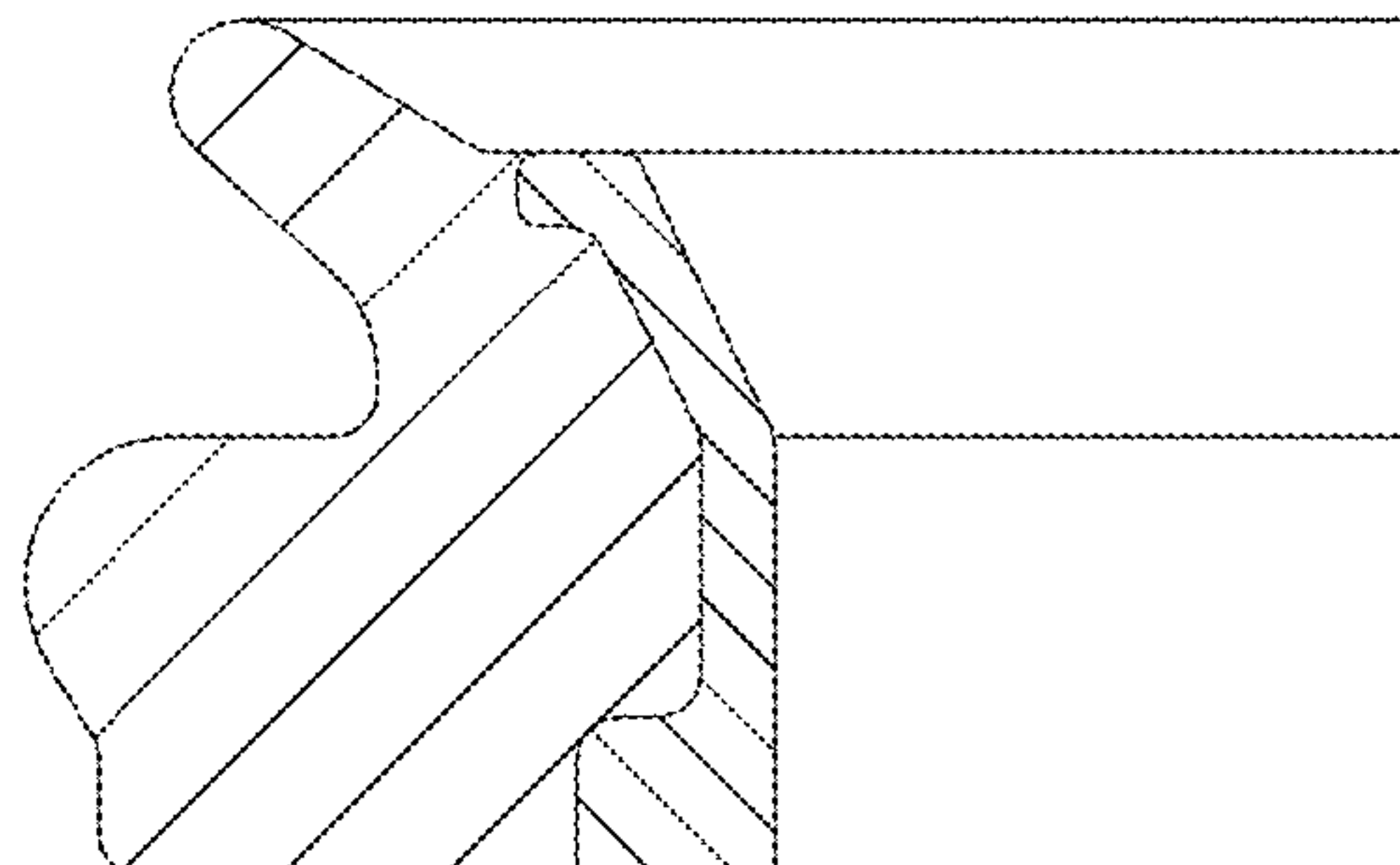
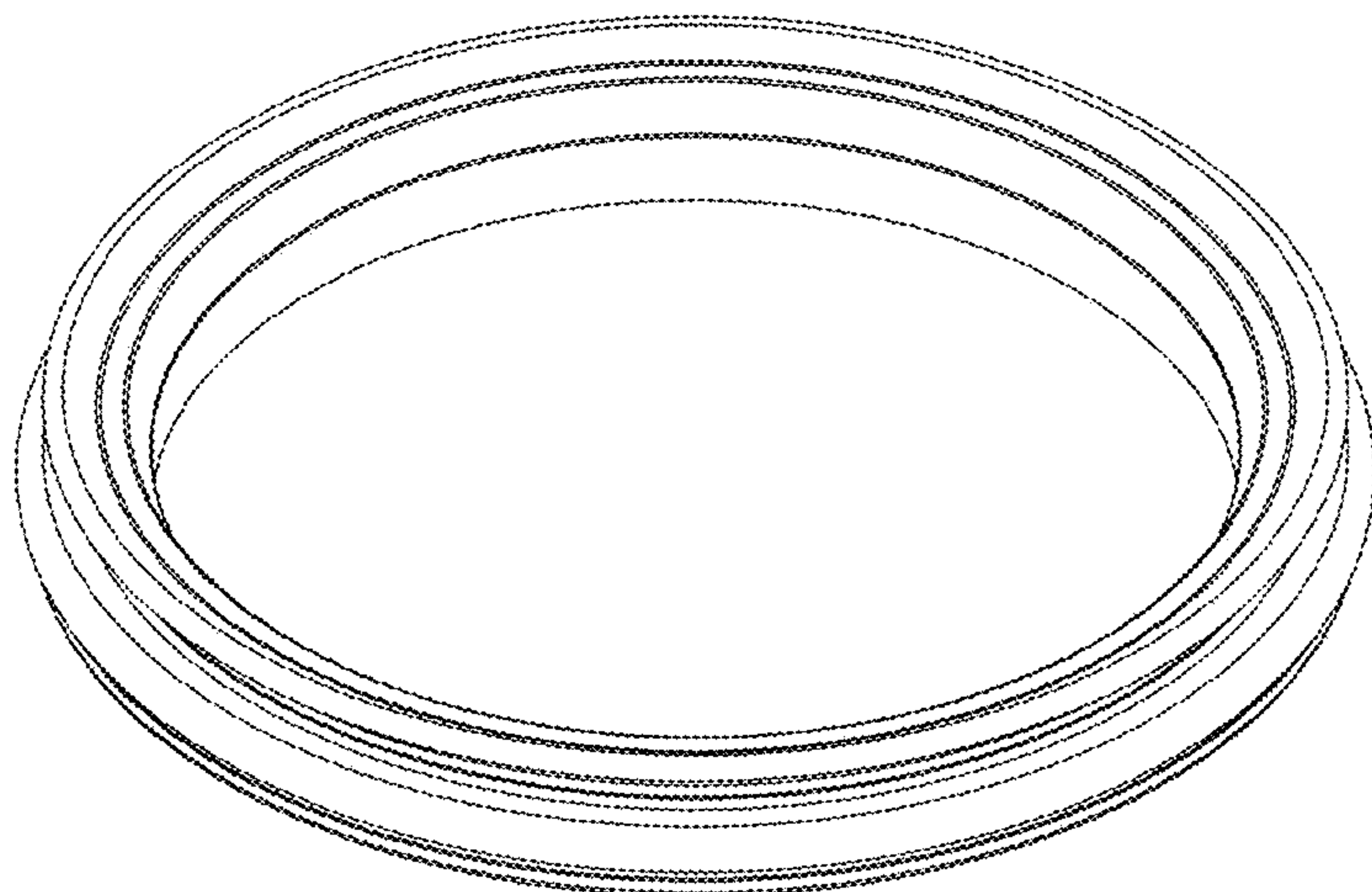
1.8 : Cross-sectional

1.9 : Partial enlargement of cross-sectional view 1.8

1.10 : Reference

The present article is a composite seal member for semiconductor production apparatuses, such as chemical vapor deposition apparatuses and dry etching apparatuses; as illustrated in the reproduction 1.10, the article is composed of a first component formed of rubber occupying a major part of the article and a second component formed of a synthetic resin, and is to be inserted into the groove of a semiconductor production apparatus; the semiconductor production apparatus itself forms no part of the claimed design; the reproduction 1.8 shows a transverse cross-sectional front view taken along the horizontal center of the reproduction 1.6; and the reproduction 1.9 is an enlarged view showing a left end portion of the cross-sectional view 1.8.

(Continued)



The broken lines shown in Reproduction 1.10 are for the purposes of illustrating environmental structure and form no part of the claimed design.

1 Claim, 10 Drawing Sheets

(58) Field of Classification Search
CPC F16J 15/32; Y10T 428/215
See application file for complete search history.

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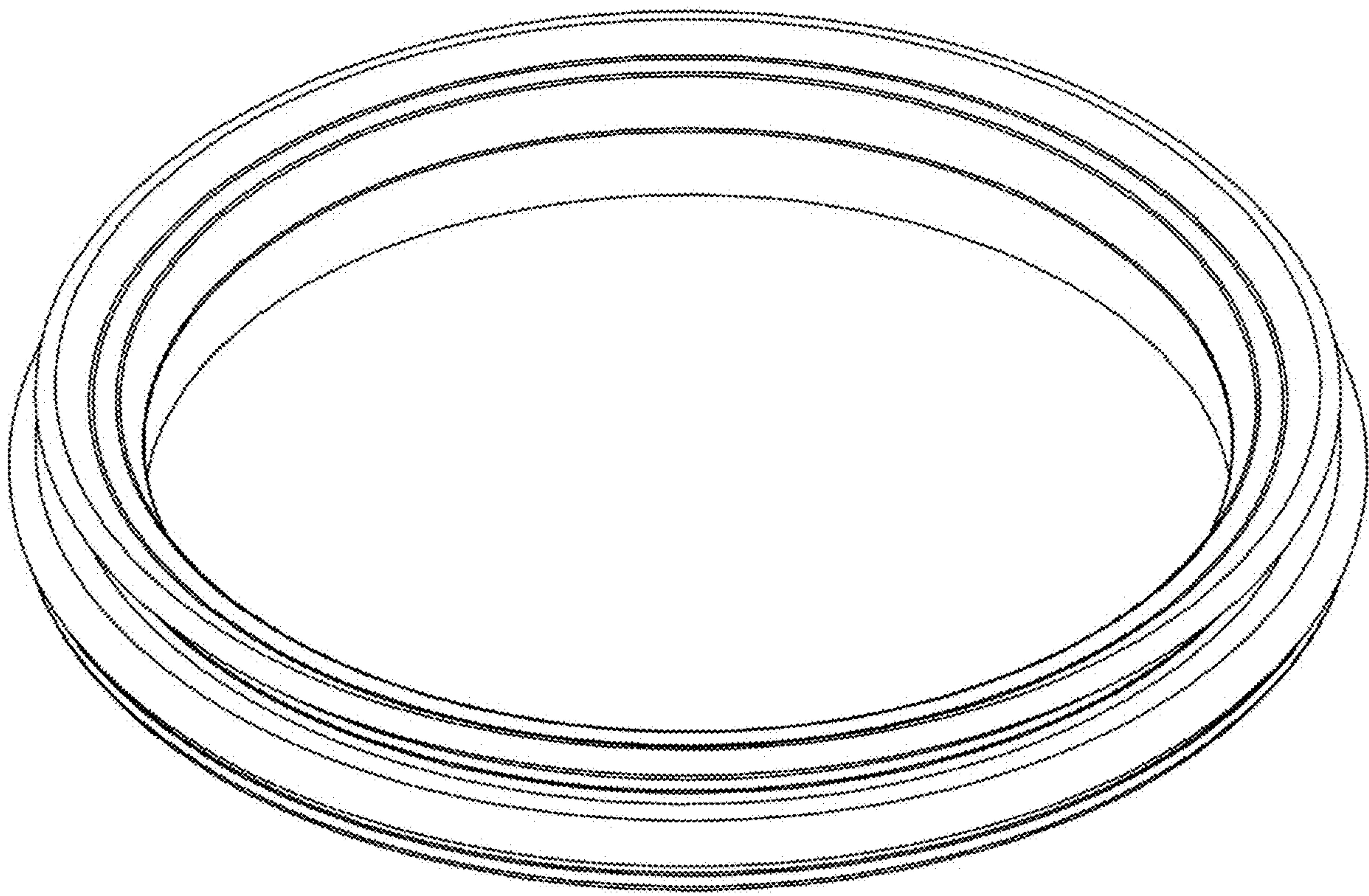
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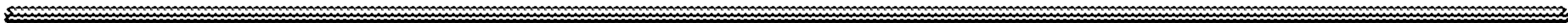
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1.1

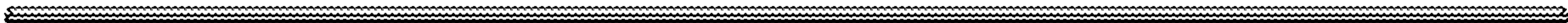


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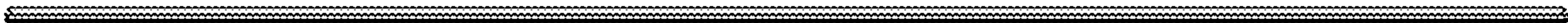
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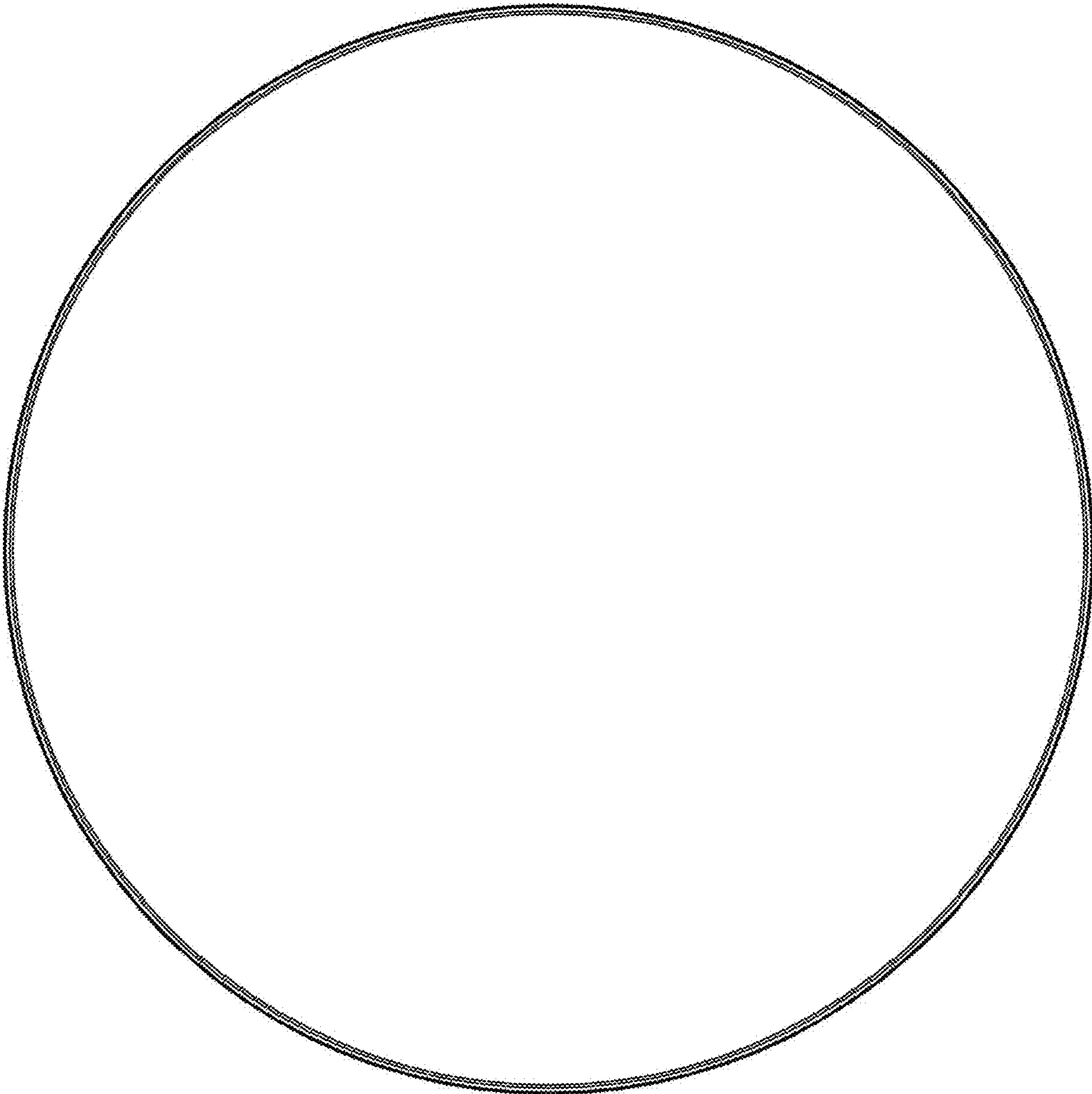
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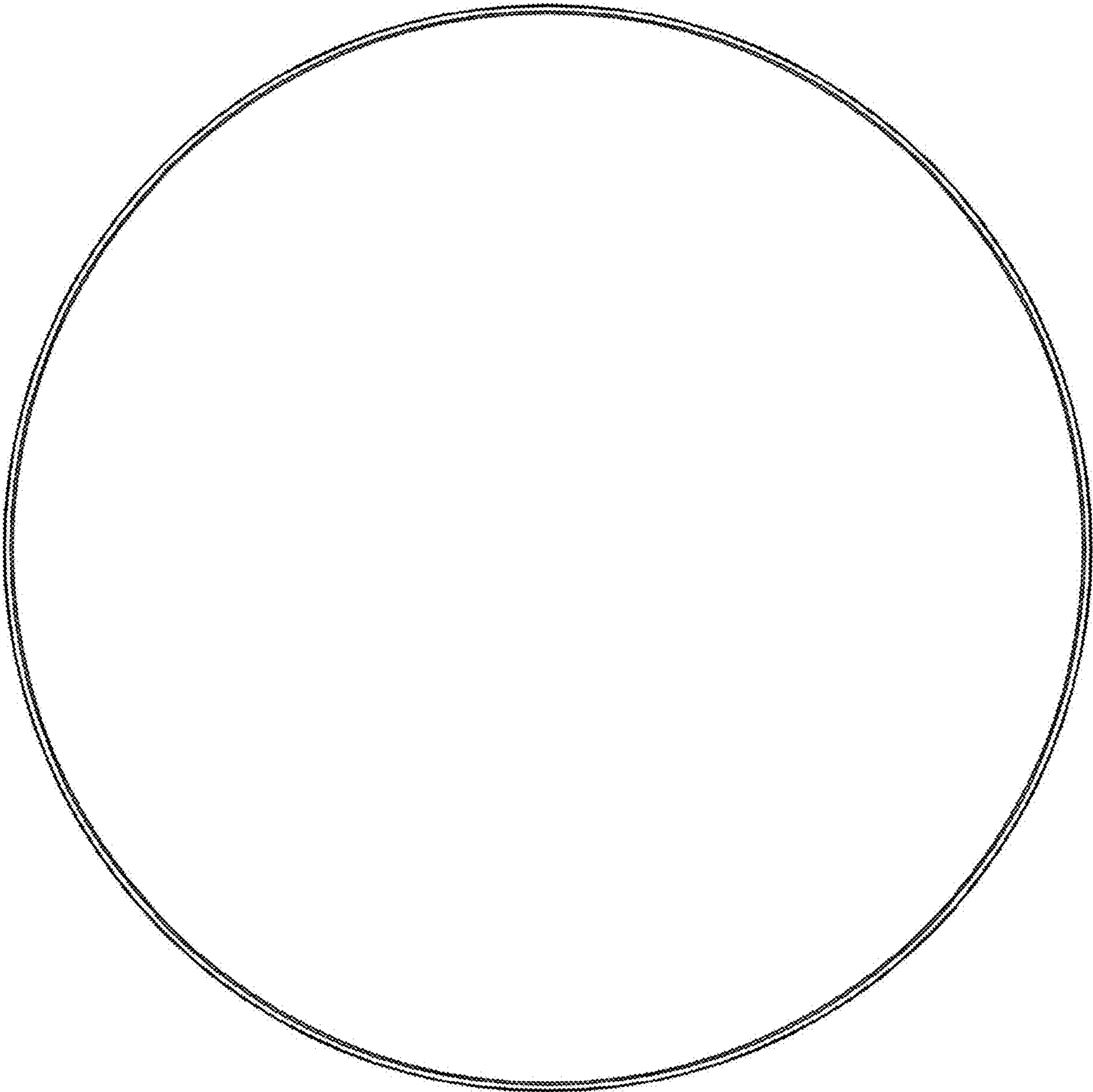
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1.6



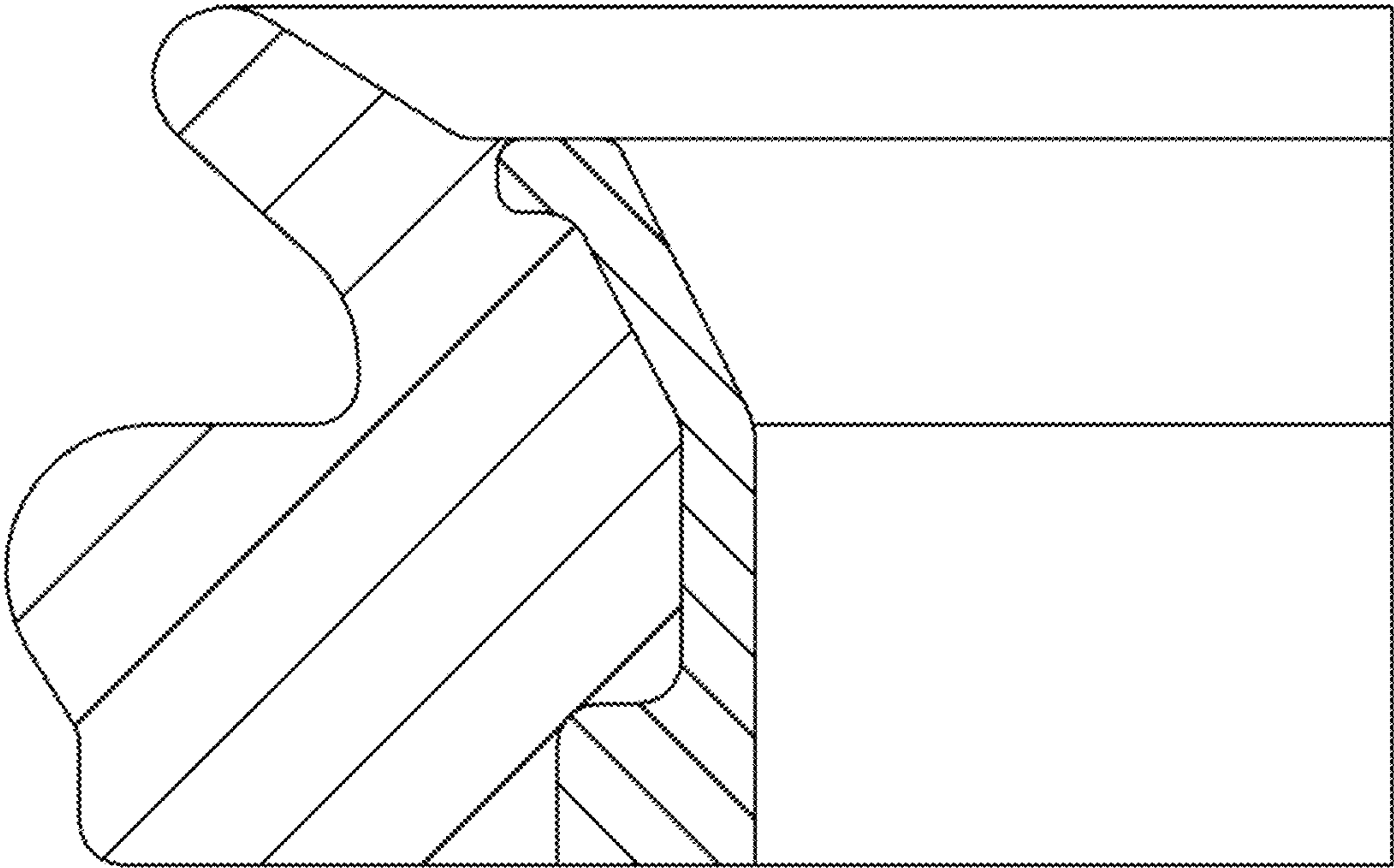
1.7



1.8



1.9



1.10

